

QFN Style Solder-Down Computer On Module

- 29mm square
- 2.6mm total height
- QS family pin-compatible
- Solder-down version
- QFN type lead style
 - 1mm pitch
 - 108 pads
 - Thermal pad
- Visual solder joint inspection possible after soldering
- Single-sided assembly
- 3.3V power supply



Key Features

- STM32MP255 Dual ARM® Cortex®-A35, 1.5 GHz
ARM® Cortex®-M33, 400 MHz
Vivante® NPU, 1.35 TOPS
- RAM 1 GB LPDDR4
- ROM 4 GB eMMC
- Grade Industrial
- Temperature -40°C to 85°C
- Display support
 - LVDS Display Interface
 - 3D GPU: OpenGL® ES 3.1 - Vulkan 1.1, OpenCL™ 1.2, OpenVX™ 1.1, Up to 149 Mtriangle/s, 900 Mpixel/s
 - VPU: H264/VP8 up to FHD (1920×1080)@60 fps
- Connectivity
 - 2x USB 2.0 + PCIe or 1x USB 2.0 + 1x USB 3.0
 - 2x Gb Ethernet, RGMII
 - 1x eMMC/SD
 - 3x CAN-FD
 - 3x UART, 3x I²C, 2x SPI, PWM, SAI
 - Up to 60x 3.3V General Purpose I/O
 - MIPI-CSI (2-lane)

OS Support

- Linux

**Dual
Cortex®-A35
STM32MP2**



STM32MP255F

System Power Supply Regulators Crystal & Internal oscillators Cyclic Redundancy Check (CRC) Watchdogs (I & W) 96-bit unique ID Up to 176 GPIOs	Dual Cortex-A35 @ 1.2GHz / up to 1.5GHz Core 1 @ 1.5GHz L1 32kB I / 32kB D Core 2 @ 1.5GHz L1 32kB I / 32kB D NEON SIMD MPE NEON SIMD MPE 512kB L2 cache TrustZone	Multimedia / AI 3D GPU: OpenGL ES3.1 / Vulkan 1.1 / OpenCL 1.2 AI / NN HW Acceleration: up to 1.35 TOPS 1080p60 H.264, VP8 Video Decoder / Encoder 24b RGB Disp. 1080p @ 60fps LVDS Display 8 lanes with PHY DSI Display 4 lanes with PHY Camera I/F MIPI CSI-2, 2 lanes Lite-ISP (Camera Pipeline) Camera I/F 16-bit Parallel
Security RIF: Isolation and safe sharing of system resources Octal SPI OTF Decryption DRAM OTF Encryption/Dec. DES, TDES, AES-256 with SCA SHA-256/512, SHA-3, HMAC PKA ECC/RSA with SCA 16x Tamper pins T°, V, F and 32KHz detection Secure RTC Analog true RNG	Cortex-M33 @ 400MHz 16 kB I-Cache 16 kB D-Cache FPU / MPU / NVIC TrustZone	Connectivity 1Gbps ETH/TSN port 1Gbps ETH/TSN port 3x CAN-FD / TTCAN PCIe Gen2, 1 lane + USB2.0 Host/Device HS or USB3.0 DRD 3x SDIO3.0 / SD 3 / eMMC 5.1 16-bit SLC NAND, 8-bit-ECC USB2.0 Host HS + HS PHY 2x Octal SPI, 8x SPI USB Type-C connector support 5x UART, 4x USART 4x I ² C, 4x I ³ C, 3x I ^S S
	DDR4/LPDDR4 32b @ 1.2GHz DDR3(L) 32b @ 1066MHz Shared RAM 640kB including 128kB Retention RAM Backup RAM 8kB / Boot ROM 128kB / OTP fuse 12kb	Audio SPDIF Rx 4 inputs 4x SAI MDF 8 channels / 8 filters
	Control 3x 16-bit motor control PWM synchronized AC timer 10x 16-bit timer 5x 16-bit LP timer 4x 32-bit timer	Analog 3x 12-bit ADC 5 MSPS Temperature sensor

QS93 | QSMP-23 | QSMP-25 | Differentiating Features

	QS93 i.MX 9352	QSMP-23 STM32MP235	QSMP-25 STM32MP255
Primary Arm® Core	2x Cortex®-A55 1.5 GHz	2x Cortex®-A35 1.2 GHz	2x Cortex®-A35 1.5 GHz
Secondary Arm® Core	Cortex-M33 250 MHz	Cortex-M33 400 MHz	Cortex-M33 400 MHz
RAM	1GB LPDDR4	1GB LPDDR4	1GB LPDDR4
ROM	4 GB eMMC	4 GB eMMC	4 GB eMMC
GPU	2D GFX	66 MTrg/s 400 MPix/s 12.8 GFlops	133 MTrg/s 800 MPix/s 25.6 GFlops
AI/ML/DSP	0.5 TOPS	0.6 TOPS	1.2 TOPS
VPU	-	Decode	De-/Encode
Connectivity	USB 2.0	USB 2.0	USB 2.0, USB 3.0 or PCIe
QS Size	100 pins 27mm square	100 pins 27mm square	108 pins 29mm square
Grade / Temperature	Industrial -40°C to 85°C	Industrial -40°C to 85°C	Industrial -40°C to 85°C

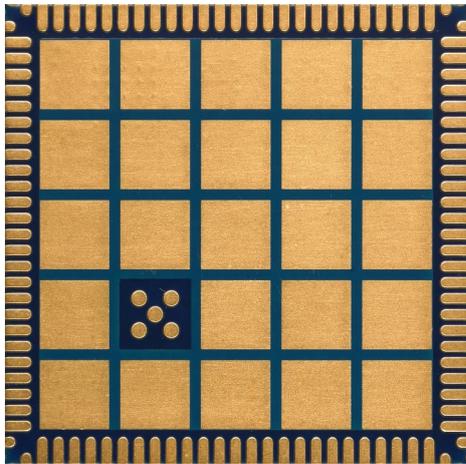
QFN Style Computer On Module Advantages

Defined Return Path

The reason PCB layout becomes more and more important is because of the trend to faster, higher integrated, smaller formfactors, and lower power electronic circuits. The higher the switching frequencies are, the more radiation may occur on a PCB. With good layout, many EMI problems can be minimized to meet the required specifications.

When a module or component is used in a design, the supplier specifies the basis for such a layout. It's not only the pinout which should lead to an easy wiring without the need for crossings. He also has to provide a proper solution for the signal path back to the module. If this return path, mostly the ground plane, cannot be connected near the signal pin, the return current has to take another way and this may result in a loop area. The larger the area, the more radiation and EMI problems may occur.

Ka-Ro QSCOM modules uses a large ground pad on the bottom side. With this a defined ground plane connection is available for all signals. In addition to have a good return path for all signals this large ground pad can be used for cooling.



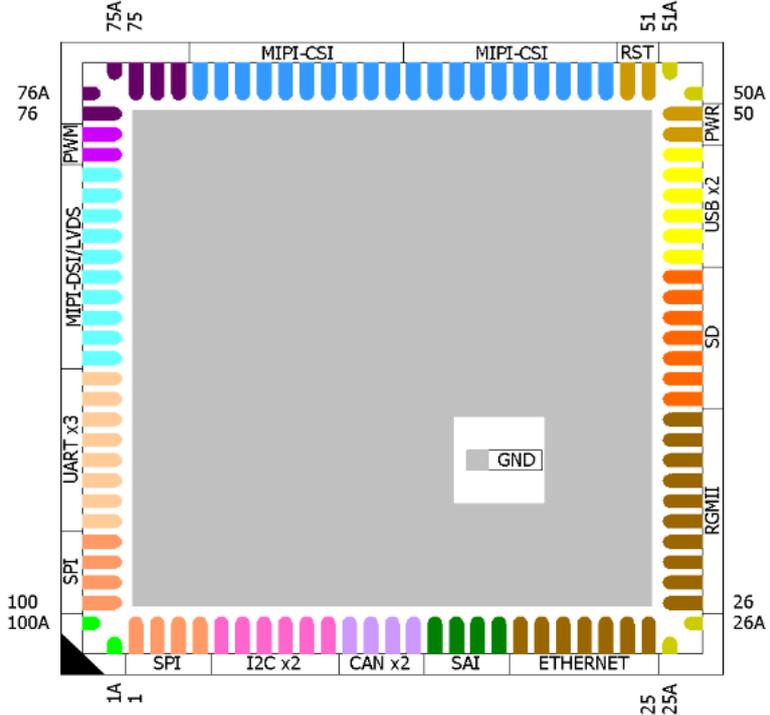
Easy Wiring - Even 2-layer printed circuit boards can be used.

With a solid ground plane on the bottom layer, high speed signals can be routed on the top layer at a defined impedance. However, this is only possible if a peripheral or plug can be connected directly without crossing other routes.

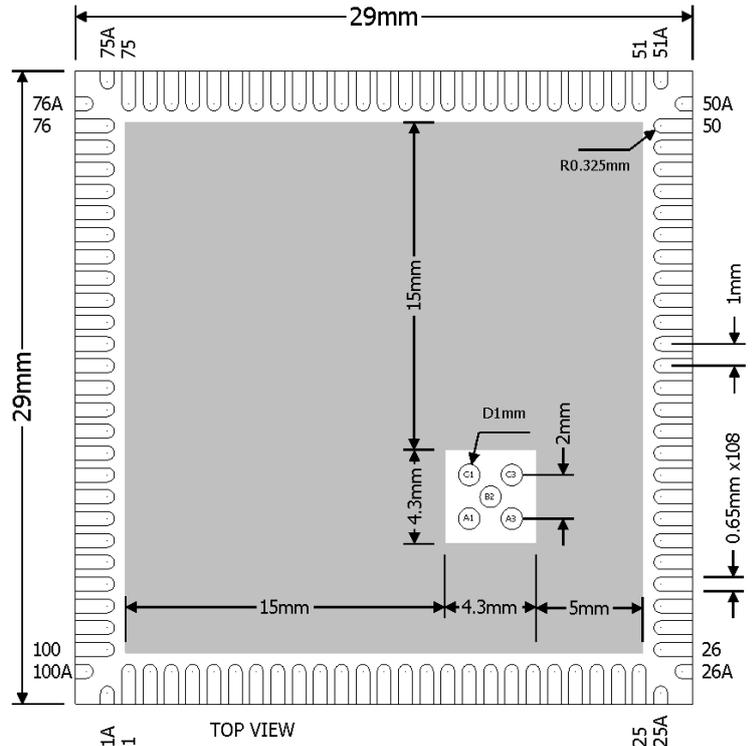
Advanced Soldering

Using a large solder pad underneath the component has not only electrical and thermal advantages. It is also used to hold the component at a defined height during soldering, without the solder being compressed by the weight of the components, which could result in short circuits.

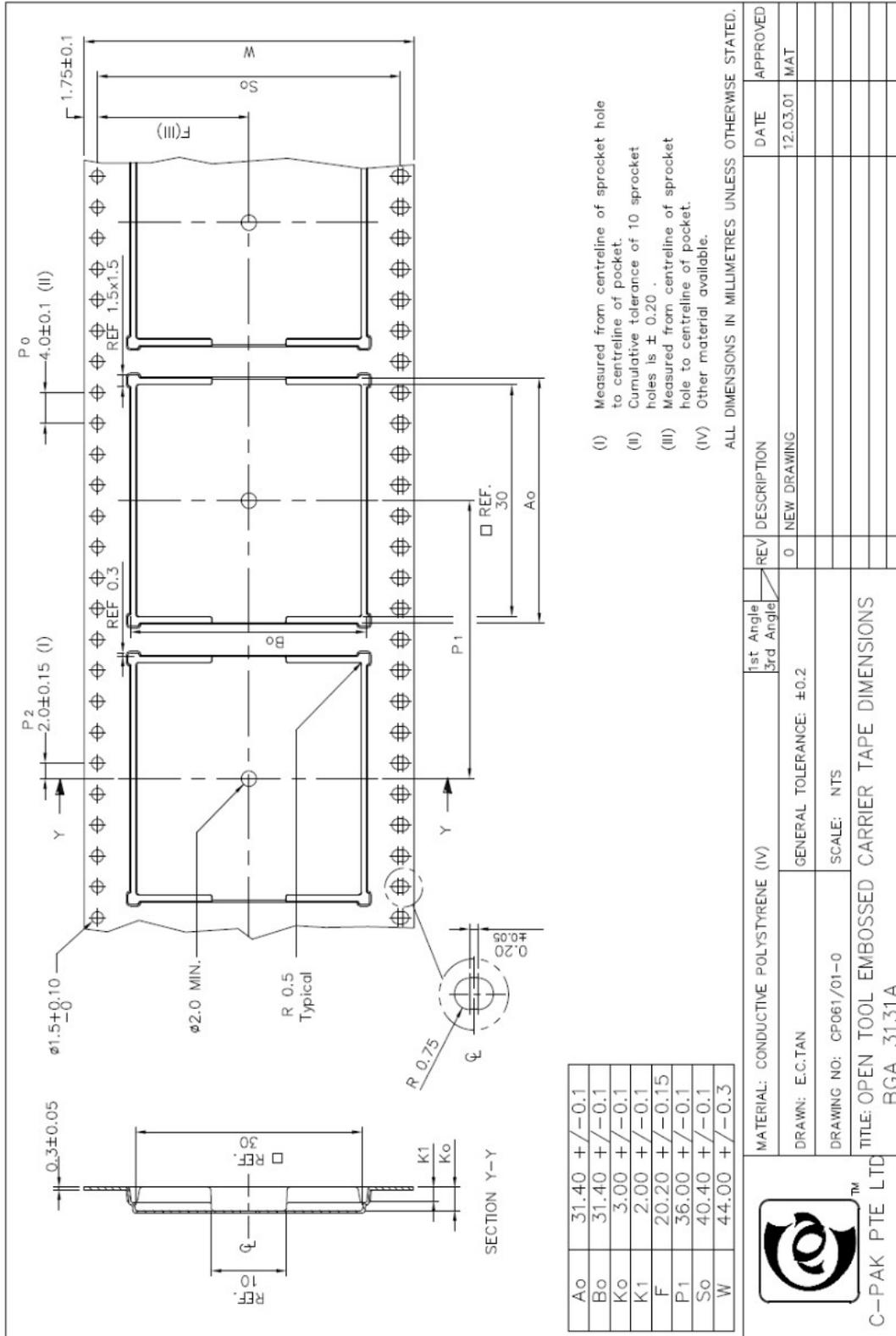
Standard Contact Assignments



Package Information



Packaging



PINOUT (STM32MP2 pads named PA, PB, etc. can be used as GPIO ports)							
IN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
1st SPI							
1	SPIA_NSS	PD5	TRACED1 SPI4_NSS HDP4 SAI1_D4	SAI1_FS_B - - -	TIM1_CH3N TIM4_CH2 OCTOSPIM_P1_IO1 -	- DCMI/PSSI/DCMIPP_D13 - EVENTOUT	
2	SPIA_MISO	PD4	DEBUG_TRACED0 SPI4_MISO HDP_HDP3 SAI1_D3	SAI1_SD_B - - -	TIM1_CH4N TIM4_CH1 OCTOSPIM_P1_IO0 -	- DCMIPP_D14/PSSI_D14 - EVENTOUT	
3	SPIA_MOSI	PD6	TRACED2 SPI4_MOSI HDP5 -	SAI1_SCK_B MDF1_SDI2 - -	TIM1_CH2N TIM4_CH3 OCTOSPIM_P1_IO2 -	DCMI/PSSI/DCMIPP_D12 - EVENTOUT	
4	SPIA_SCK	PD7	TRACED3 SPI4_SCK SPI1_RDY -	SAI1_MCLK_B MDF1_CK12 - -	TIM1_CH1N TIM4_CH4 OCTOSPIM_P1_IO3 -	- DCMI/PSSI/DCMIPP_D11 - EVENTOUT	
I2C							
5	I2CA_SCL	PB5	- - I2S2_MCK UART4_DE/UART4_RTS	SAI4_SD_B MDF1_CK14 - -	TIM20_CH1 I2C2_SCL OCTOSPIM_P2_IO5 -	FMC_D8/FMC_DA8 I3C2_SCL SDMMC3_D123DIR EVENTOUT	
6	I2CA_SDA	PB4	- - SPI2_RDY UART4_CTS	SAI4_FS_B MDF1_SDI4 TIM14_CH1 -	TIM20_CH2 I2C2_SDA OCTOSPIM_P2_IO4 -	- I3C2_SDA - EVENTOUT	
7	INTA	PD15	- - SPI1_RDY -	DSIHOST_TE I2C5_SDA FDCAN1_TX -	TIM1_BKIN2 TIM5_ETR I2C7_SCL FMC_D3/FMC_DA3	SDMMC3_CKIN DCMIPP_D0/DCMI_D0/PSSI_D0 - EVENTOUT	
8	I2CB_SCL	PG6	TRACED4 HDP4 SPI5_SCK SPI1_SCK/I2S1_CK	- - - TIM2_CH4	- I2C6_SCL - -	- LCD_R6 DCMI/PSSI/DCMIPP_DE EVENTOUT	
9	I2CB_SDA	PG5	TRACED3 HDP3 - USART6_RTS	- - - TIM2_CH3	- I2C6_SDA - -	- LCD_R5 DCMI/PSSI/DCMIPP_PCLK EVENTOUT	
10	INTB	PD14	- - I2S1_MCK -	- - - FDCAN1_RX	TIM11_CH1 - I2C7_SDA FMC_D4/FMC_DA4	SDMMC3_D3 DCMIPP_D1/PSSI_D1 - EVENTOUT	
CAN							
11	CANA_RX	PB11	- - I2S3_MCK -	- - USART1_CTS/USART1_NSS FDCAN1_RX	TIM20_BKIN2 TIM12_CH2 OCTOSPIM_P2_NCLK OCTOSPIM_P2_NCS2	FMC_AD14/FMC_D14 OCTOSPIM_P1_NCS2 - EVENTOUT	
12	CANA_TX	PB9	- - SPI3_RDY -	- - USART1_RTS FDCAN1_TX	TIM20_BKIN TIM10_CH1 OCTOSPIM_P2_DQS OCTOSPIM_P2_NCS2	FMC_D13/FMC_DA13 - - EVENTOUT	
13	CANB_RX	PI10	- - SAI1_SCK_A SPI1_SCK/I2S1_CK SPDIFRX1_IN0	- - FDCAN2_RX MDF1_CCK0 -	- - - TIM4_CH1 SDVSEL1 - -	FMC_AD12/FMC_D12 DSI_TE - EVENTOUT	
14	CANB_TX	PI9	- - SPI7_MOSI SPI2_MOSI/I2S2_SDO	- - FDCAN2_TX - UART9_CTS	TIM16_BKIN SDVSEL2 FMC_NWAIT -	- LCD_B0 - EVENTOUT	
SAI							
15	SAI_TX	PD1	- - HDP_HDP1 I2S1_SDI/SPI1_MISO SAI1_CK2	- - SAI4_SD_A UART7_DE/UART7_RTS TIM15_CH1	TIM1_BKIN FDCAN3_RX OCTOSPIM_P1_NCLK OCTOSPIM_P1_NCS2	OCTOSPIM_P2_NCS2 DCMIPP_HSYNC/PSSI_DE - EVENTOUT	
16	SAI_RX	PI3	- - - LPTIM1_IN2	- - SAI4_SD_B - USART1_CTS	TIM8_CH2 - - -	- LTDC_B6 DCMIPP_D14/PSSI_D14 EVENTOUT	
17	SAI_SCK	PD2	- - HDP_HDP2 I2S1_WS/SPI1_NSS SAI1_CK1	- - SAI4_SCK_A UART7_CTS TIM15_BKIN	TIM1_ETR FDCAN3_TX OCTOSPIM_P1_DQS OCTOSPIM_P1_NCS2	- DCMIPP_VSYNC/PSSI_RDY - EVENTOUT	

IN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
18	SAI_FS	PD0	DEBUG_TRACECLK HDP_HDP0 SPI7_RDY SAI1_D2	- SAI4_FS_A UART7_RX TIM15_CH2	- - OCTOSPIM_P1_CLK -	- - DCMIPP_PIXCLK/PSSI_PDCK - EVENTOUT	
ETHERNET 1							
19	ENET_RST	PB2	- - I2S2_SDO/SPI2_MOSI	- MDF1_CK13 TIM17_BKIN TIM16_BKIN	- - TIM20_CH2N - OCTOSPIM_P2_IO2	- - - -	
20	ENET_CK125	PH9	- - SPI6_NSS	- SAI3_MCLK_A - USART6_RX TIM15_CH1N	- - - ETH1_CLK125 ETH1_RX_ER	- - - - EVENTOUT	
21	ENET_INT	PF5	- - SPI6_SCK	- SAI3_MCLK_A - USART6_TX TIM4_CH3	- - ETH1_MDIO ETH1_CLK ETH2_PHY_INTN ETH1_PHY_INTN	- - - - LTDC_B6	
22	ENET_MDIO	PA10	- - SPI4_MISO	- SAI2_SD_B - USART2_RX LPTIM5_IN1	- - TIM2_CH2 - ETH1_MDIO	- - - - LTDC_R6 DCMIPP_D15/PSSI_D15 ETH3_RXD1	
23	ENET_MDC	PF4	- RTC_OUT2 SPI6_NSS	- USART6_RX TIM4_CH4	- - ETH1_MDC ETH2_CLK ETH2_PPS_OUT ETH1_PPS_OUT	- - - - LTDC_B7	
24	ENET_RXC	PA14	- SPI8_NSS LPTIM2_CH2	- SAI4_FS_B MDF1_CCK1	- - - ETH1_RX_CLK/REF_CLK	- - - - EVENTOUT	
25	ENET_RX_CTL	PA11	- SPI8_SCK LPTIM2_CH1	- SAI4_SD_B MDF1_SDI4	- - - ETH1_RXDV/RXCTL/CRSDV	- - - - EVENTOUT	
26	ENET_RXD0	PF1	- SPI8_MISO LPTIM2_IN2	- SAI4_SCK_B MDF1_CK14 USART2_CK	- - - ETH1_RXD0	- - - - EVENTOUT	
27	ENET_RXD1	PC2	- SPI8_MOSI LPTIM2_IN1	- SAI4_MCLK_B MDF1_SDI3 USART2_RTS	- - - ETH1_RXD1	- - - - EVENTOUT	
28	ENET_RXD2	PH12	- - SPI3_NSS/I2S3_WS SPI6_MISO	- - - -	- - - TIM10_CH1	- - - - ETH1_RXD2	- - - - EVENTOUT
29	ENET_RXD3	PH13	- - SPI3_SCK/I2S3_CK SPI6_MOSI	- - - TIM15_BKIN	- - - ETH1_RXD3	- - - - EVENTOUT	
30	ENET_TX_CTL	PA13	- SPI8_RDY I2S3_MCK LPTIM2_ETR	- MDF1_CK13 USART2_CTS/USART2_NSS	- - I2C7_SMBA ETH1_TX_EN/TX_CTL	- - - - EVENTOUT	
31	ENET_TXC	PC0	- LPTIM1_CH1 - SPI6_SCK	- SAI3_MCLK_B USART6_TX - -	- - DCMI/PSSI/DCMIPP_D0 ETH2_RX_CLK/REF_CLK ETH1_TX_CLK	- - - - ETH1_GTX_CLK LCD_G7 - EVENTOUT	
32	ENET_TXD3	PH11	- - SPI6_MISO	- SAI3_FS_A - - TIM15_CH2	- - ETH2_MDIO ETH1_TXD3	- - - - EVENTOUT	
33	ENET_TXD2	PH10	- - SPI1_SCK/I2S1_CK SPI6_MOSI	- SAI3_SCK_A - - TIM15_CH1	- - ETH2_MDC ETH1_TXD2	- - - - EVENTOUT	
34	ENET_TXD1	PC1	- - SPI3_MOSI/I2S3_SDO	- - USART2_TX	- - I2C7_SCL ETH1_TXD1	- - - - EVENTOUT	
35	ENET_TXD0	PA15	- - SPI3_MISO/I2S3_SDI	- - USART2_RX	- - I2C7_SDA ETH1_TXD0	- - - - EVENTOUT	
SD							
36	SD_CD	PA4	- - - -	- - USART2_TX FDCAN2_TX	- - TIM2_CH1 - LTDC_R1 -	- - - - ETH1_PTP_AUX_TS ETH3_PPS_OUT	

IN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
37	SD_D1	PE5	TRACED1 LPTIM2_IN2 SPI1_NSS/I2S1_WS SPI3_NSS/I2S3_WS	SAI1_FS_B - USART3_RTS FDCAN1_RX	- - SDMMC1_D1 -	- - - EVENTOUT	
38	SD_D0	PE4	TRACED0 LPTIM2_IN1 SPI1_MOSI/I2S1_SDO SPI3_MISO/I2S3_SDI	SAI1_SD_B - USART3_CTS/USART3_NSS FDCAN1_TX	- - SDMMC1_D0 -	- - - EVENTOUT	
39	SD_CLK	PE3	TRACECLK - SPI1_RDY SPI3_SCK/I2S3_CK	SAI1_MCLK_B - USART3_TX -	TIM11_CH1 - SDMMC1_CK -	- - - EVENTOUT	
40	SD_CMD	PE2	- LPTIM2_ETR SPI1_MISO/I2S1_SDI SPI3_MOSI/I2S3_SDO	SAI1_SCK_B - - -	TIM10_CH1 - SDMMC1_CMD -	- - - EVENTOUT	
41	SD_D3	PE1	TRACED3 LPTIM2_CH2 I2S1_MCK I2S3_MCK	- - USART3_RX -	- - SDMMC1_D3 -	- - - EVENTOUT	
42	SD_D2	PE0	TRACED2 LPTIM2_CH1 SPI1_SCK/I2S1_CK SPI3_RDY	- - USART3_CK -	- - SDMMC1_D2 -	- - - EVENTOUT	

USB

43	USBA_VBUS	UCPD1_CC2					
44	USBA_DN	USBH_HS_DM					
45	USBA_DP	USBH_HS_DP					
46	USBB_VBUS	UCPD1_CC1					
47	USBB_DN	USB3DR_DM					
48	USBB_DP	USB3DR_DP					

POWER SUPPLY & RESET

49	VIN	3.3V power supply input					
50							
51	NRST	Open drain reset to reset of external devices, or to reset the device. Connected to STM32MP2 NRST and PCA9450 POR_B, 10K-PU					
52	BOOT_MODE	Connected to STM32MP2 BOOT1, 10K-PU. BOOT[0,2,3]=L					H: Boot from eMMC L: Boot from USB

MISC

53		PB15	- LPTIM1_IN2 SPI5_SCK UART8_DE/UART8_RTS	SAI2_SD_B UART5_RX - TIM3_CH2	TIM5_CH1 - ETH1_PPS_OUT -	FMC_A18 LTDC_R4 DCMIPP_D8/PSSI_D8 EVENTOUT	
54		PF3	- - UART8_RX	SAI2_SCK_B MDF1_CCK0 - TIM3_CH4	TIM8_BKIN2 ETH1_CLK ETH2_PPS_OUT -	FMC_A20 LTDC_R6 DCMIPP_HSYNC/PSSI_DE EVENTOUT	
55		PG3	- LPTIM1_ETR SPI5_MOSI UART8_TX	SAI2_FS_B - - TIM3_CH3	TIM8_ETR ETH2_CLK ETH2_PHY_INTN -	FMC_A19 LTDC_R5 DCMIPP_PIXCLK/PSSI_PDCK EVENTOUT	
56		PG2	- RTC_REFIN I2S3_MCK I3C3_SDA	SAI2_FS_A - USART3_CK -	TIM5_CH3 I2C3_SDA ETH2_MII_TX_CLK ETH2_RGMII_CLK125	FMC_CLK LTDC_HSYNC - EVENTOUT	

MIPI-CSI

57	CSI1_D1_P	CSI_D1P					
58	CSI1_D1_N	CSI_D1N					
59	CSI1_D0_P	CSI_D0P					
60	CSI1_D0_N	CSI_D0N					
61	CSI1_CLK_P	CSI_CKP					
62	CSI1_CLK_N	CSI_CKN					

IN	QSCOM STANDARD	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-15	Remarks Additional functions
85	DSI_DP0 LVDS_TX0P	LVDS_D0P					
86	DSI_DN0 LVDS_TX0N	LVDS_D0N					
87	DSI_CKP LVDS_CLKP	LVDS_D4P					
88	DSI_CKN LVDS_CLKN	LVDS_D4N					

UART

89	UARTA_RXD	PB6	- I2S2_SDI/SPI2_MISO UART4_RX	SAI4_SCK_B - -	TIM20_CH1N - OCTOSPIM_P2_IO6 -	FMC_D9/FMC_DA9 - SDMMC3_D0DIR EVENTOUT	
90	UARTA_TXD	PB7	- I2S3_CK/SPI3_SCK UART4_TX	SAI4_MCLK_B - -	TIM20_ETR TIM12_CH1 OCTOSPIM_P2_IO7 -	FMC_D10/FMC_DA10 - SDMMC3_CDIRE EVENTOUT	
91	UARTB_RXD	PI7	- - -	- - USART3_RX TIM2_CH1	- - - TIM3_CH2	- - - LTDC_HSYNC EVENTOUT	
92	UARTB_TXD	PI6	- RCC_MCO_1 - -	- - USART3_TX TIM2_ETR	- - - TIM3_CH1	- - - LTDC_VSYNC EVENTOUT	
93	UARTC_RXD	PG10	- DEBUG_TRACED8 HDP_HDP0 - -	- - UART5_RX -	- - - TIM8_CH4N	- - - LTDC_G4 DCMIPP_D4/PSSI_D4 EVENTOUT	
94	UARTC_TXD	PG9	- DEBUG_TRACED7 - - -	- - UART5_TX -	- - - TIM5_CH4	- - - LTDC_G3 DCMIPP_D3/PSSI_D3 EVENTOUT	
95	UARTC_CTS	PG1	- LPTIM1_IN1 I2S3_MCK I3C3_SCL	SAI2_SD_A UART5_CTS USART3_CTS	TIM5_CH4 I2C3_SCL ETH2_MII_RX_ER ETH2_RXD3	FMC_NBL0 LTDC_VSYNC DCMIPP_D11/PSSI_D11 EVENTOUT	CTS/RTS input signal
96	UARTC_RTS	PG8	- DEBUG_TRACED6 HDP_HDP6 SPI5_RDY SPI1_RDY	USART6_CK UART5_DE/ UART5_RTS UART9_TX	TIM5_CH3 - - -	- - - LTDC_G2 DCMIPP_D2/PSSI_D2 EVENTOUT	RTS/CTS output signal

2nd SPI

97	SPIB_NSS	PA8	- LPTIM2_CH2 SPI7_NSS	SAI1_FS_B - USART1_CK	USART2_RX I2C5_SCL -	LTDC_B2 DCMIPP_D4/DCMI_D4/PSSI_D4 -	
98	SPIB_MISO	PD12	- SPI7_MISO I2S2_SDI/SPI2_MISO SPDIFRX_IN2	UART8_DE/UART8_RTS - -	TIM4_ETR SDMMC3_CMD FMC_D6/FMC_DA6	FMC_D1/FMC_DA1 - -	
99	SPIB_MOSI	PG11	- DEBUG_TRACED9 HDP_HDP1 SPI7_MOSI	- - -	TIM8_CH4 - -	- - LTDC_G5 DCMIPP_D5/PSSI_D5	
100	SPIB_SCK	PB13	- - SPI7_SCK	FDCAN1_TX SAI1_SD_B UART8_RX	- - -	FMC_D0/FMC_DA0 - -	

USB3/PCIe

25A		PCIE_CLKOUTN					
26A		PCIE_CLKOUTP					
50A		PB8	- I2S3_SDO/SPI3_MOSI -	PCIE_CLKREQN - USART1_TX TIM17_CH1	TIM20_CH4 - OCTOSPIM_P2_NCS1 -	FMC_D12/FMC_DA12 - - EVENTOUT	
51A		VBAT					
75A		COMBOPHY_TX1P					
76A		COMBOPHY_TX1N					
100A		COMBOPHY_RX1P					
1A		COMBOPHY_RX1N					

Pins used for manufacturing and debugging – leave unconnected

PIN	(SPM32MP2 PAD NAME)	PIN	(SPM32MP2 PAD NAME)	PIN	(SPM32MP2 PAD NAME)
C1	JTAG_TDI (JTDI)			C3	JTAG_TCK (JTCK_SWCLK)
		B2	JTAG_TDO (JTDO_TRACESWO)		
A1	JTAG_TRST_B (NJTRST)			A3	JTAG_TMS (JTMS_SWDIO)

Onboard peripherals wiring

USED FOR	MP2 PAD	Alternate Function 0-3	Alternate Function 4-7	Alternate Function 8-11	Alternate Function 12-14	Remarks
eMMC	CMD	PE15 - SPI7_MOSI - -	SAI1_SCK_A MDF1_SDI6 - TIM15_CH1N	TIM1_CH1N - FMC_NOE	SDMMC2_CMD - -	10K-PU
	CLK	PE14 - SPI7_NSS - -	SAI1_MCLK_A MDF1_CK16 - TIM15_BKIN	TIM1_BKIN - FMC_NWE	SDMMC2_CK - -	10K-PU
	DAT0	PE13 - SPI7_MISO - -	SAI1_SD_A - TIM15_CH1	TIM1_CH2N - FMC_RNB	SDMMC2_D0 - -	10K-PU
	DAT1	PE11 - SPI7_SCK SAI4_D3 -	SAI1_FS_A - TIM15_CH2	TIM1_CH3N - FMC_A16/FMC_CLE	SDMMC2_D1 - -	
	DAT2	PE8 - SPI4_MOSI - SAI4_CK1	SAI4_MCLK_A MDF1_CK10 - -	TIM1_CH1 - FMC_A17/FMC_ALE	SDMMC2_D2 - -	
	DAT3	PE12 - SPI4_NSS - SAI4_CK2	SAI4_SCK_A MDF1_SDI0 USART1_RTS -	TIM1_CH2 - FMC_NE2 FMC_NCE1	SDMMC2_D3 - -	
	DAT4	PE10 - SPI4_SCK - SAI4_D1	SAI4_SD_A - USART1_CTS -	TIM1_CH3 - FMC_NE3 FMC_NCE2	SDMMC2_D4 SDMMC2_CKIN -	
	DAT5	PE9 - SPI4_MISO - SAI4_D2	SAI4_FS_A - USART1_CK -	TIM1_CH4 - FMC_D0/FMC_DA0	SDMMC2_D5 SDMMC2_CDIR -	
	DAT6	PE6 - SPI4_RDY - -	SPDIFRX_IN2 - USART1_TX -	TIM1_ETR - FMC_D1/FMC_DA1	SDMMC2_D6 SDMMC2_D0DIR -	
	DAT7	PE7 - - SAI4_D4	SPDIFRX_IN3 - USART1_RX -	TIM1_CH4N - TIM14_CH1 FMC_D2/FMC_DA2	SDMMC2_D7 SDMMC2_D123DIR -	
PMIC PCA9450A	SDA	PI1 DEBUG_TRACED15 HDP_HDP7 SPI7_NSS -	MDF1_SDI6 - -	TIM8_CH3N I2C1_SDA I3C1_SDA -	LTDC_B4 DCMIPP_D8/PSSI_D8	1K-PU
	SCL	PG13 DEBUG_TRACED11 HDP_HDP3 SPI7_SCK -	MDF1_CK16 - -	TIM8_CH2N I2C1_SCL I3C1_SCL -	LTDC_G7 DCMIPP_D7/PSSI_D7	10K-PU
	IRQ_B	PD11 DEBUG_TRACED7 I2S1_CK/SPI1_SCK SAI1_MCLK_A	UART4_TX MDF1_CK10 I2C4_SCL -	TIM1_CH1 - OCTOSPIM_P1_IO7 SDMMC1_D4	SDMMC1_CKIN DCMIPP_D7/DCMI_D7/PSSI_D7 -	10K-PU
	POR_B	NRST				10K-PU
	PMIC_ON_REQ	PWR_ON				
	PMIC_STBY_REQ	PWR_LP				
	WDOG_B	PD8 DEBUG_TRACED4 SPI4_RDY I2S1_MCK SAI1_FS_A	UART4_CTS MDF1_SDI1 - -	TIM1_CH4 TIM4_ETR OCTOSPIM_P1_IO4 SDMMC1_D7	SDMMC1_D123DIR DCMIPP_D10/PSSI_D10 -	10K-PU

Electrical characteristics

Absolute maximum ratings

Parameter	Symbol	Min	Max	Remarks
Power supply	VIN	0V	3.7V	VDD=VIN
Input voltage on USB DN/DP pins	USBA_DN/DP USBB_DN/DP	0V	5.5V	
Input voltage on any other pins		0V	3.6V	
Storage temperature range	T _{STORAGE}	-40°C	85°C	

Operating ranges

Parameter	Symbol	Min	Max	Remarks
Power supply	VIN	3.1V	3.6V	
I/O input low level voltage	V _{IL}	-	0.3 x VIN	
I/O input high level voltage	V _{IH}	0.7 x VIN	-	
I/O output voltage	Refer to STM32MP2 datasheet, chap. Output voltage levels.			VDD=VIN=3.3V typ.
Operating temperature range	T _{AMB}	-40°C	85°C	
Processor junction temperature	T _J	-40°C	125°C	

Power supply currents

Parameter	Symbol	VIN	Current	Remarks
At U-Boot prompt	I _{UBOOT}	3.3V	245mA	All pins left unconnected
At Linux prompt	I _{LINUX}	3.3V	245mA	
Sleep	I _{SLEEP}	3.3V	24mA	
Maximum calculated	I _{MAX}	3.3V	1200mA	Calculated on max. IDD's @ 80% onboard power supply efficiency.
Power supply rating	I _{SUPP}	3.3V	1.8A	With margin for sizing the power supply